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United States Patent [19]

Ball

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[54] MULTI-CHIP STACKED DEVICES

[75] Inventor: Michael B. Ball, Boise, Id.

[73] Assignee: Micron Semiconductor, Inc., Boise, Id.

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[58] Field of Search 257/777, 782, 783, 676, 257/686

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Primary Examiner—Andrew J. James
Assistant Examiner—T. M. Arroyo
Attorney, Agent, or Firm—Hopkins, French, Crockett, Springer & Hoopes

[57] ABSTRACT

A multiple stacked die device is disclosed that contains up to four dies and does not exceed the height of current single die packages. Close-tolerance stacking is made possible by a low-loop-profile wire-bonding operation and thin-adhesive layer between the stacked dies.

2 Claims, 2 Drawing Sheets